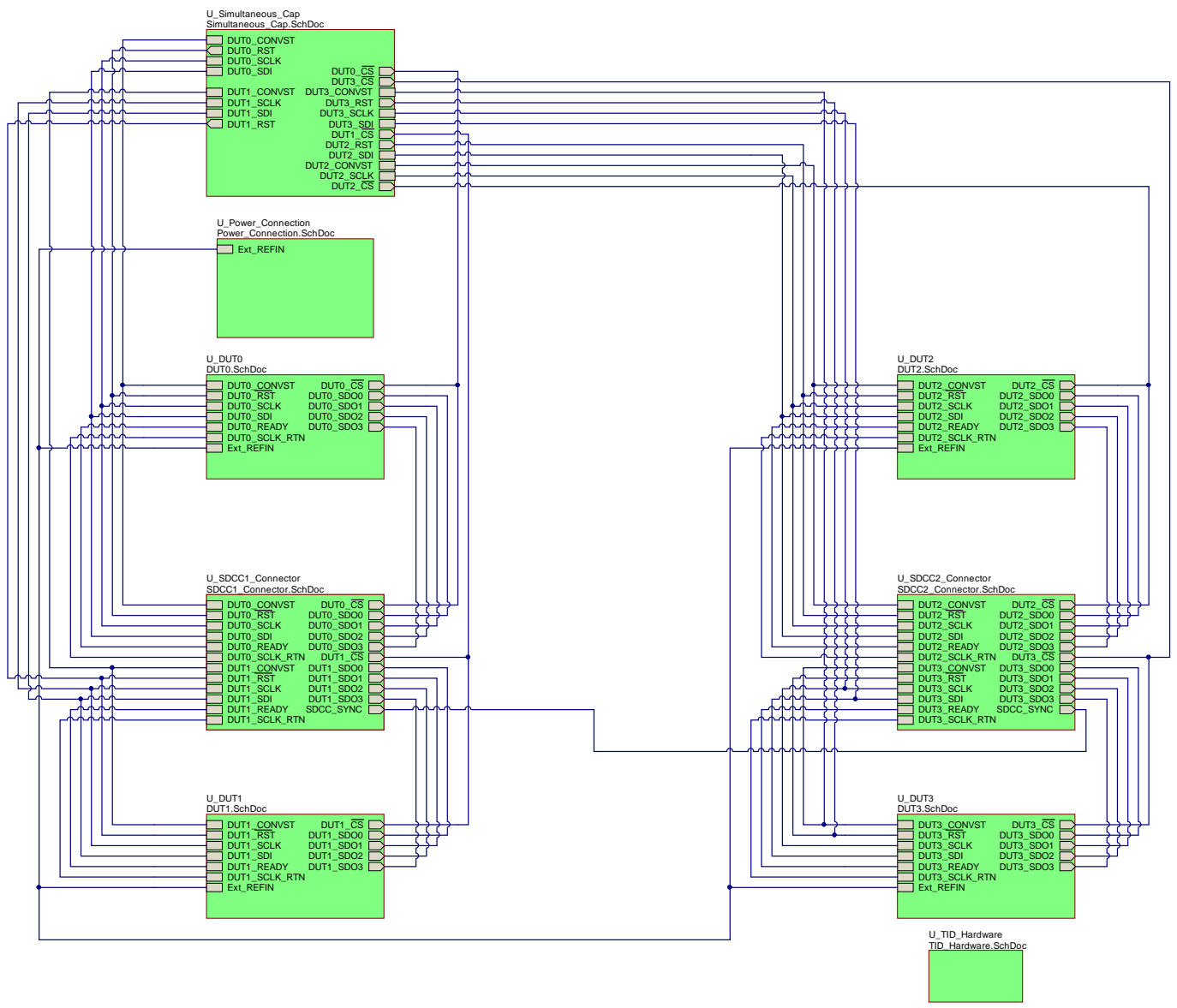
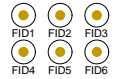
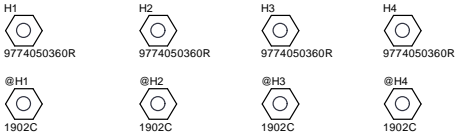


Revision History	
Revision	Notes





PCB Number: TIPD211
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

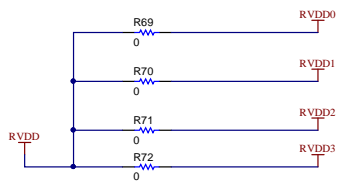
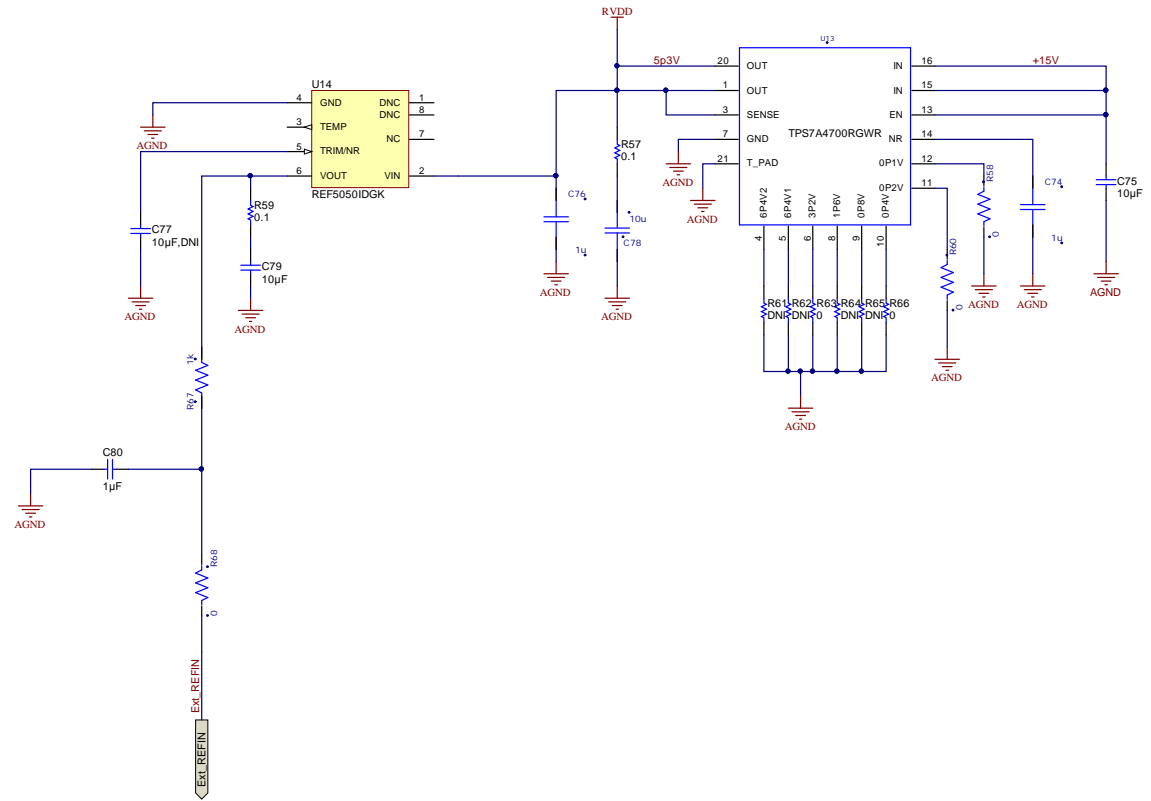
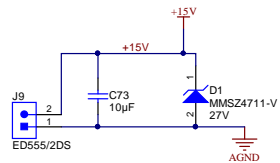
ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

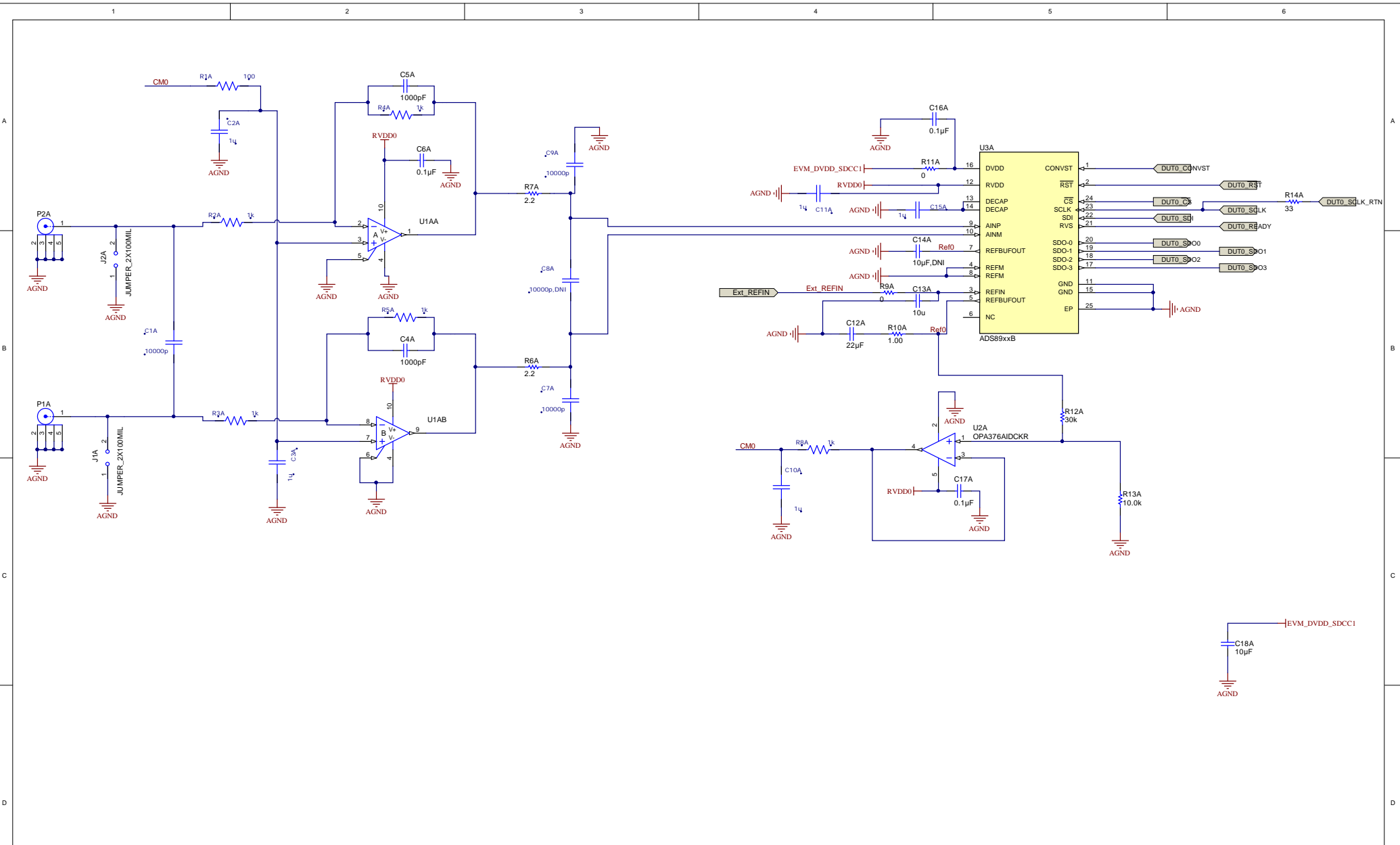
ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIPD211	Project Title: TIPD211	
Number: TIPD211 Rev: E1	Sheet Title:	Sheet: 2 of 10
Rev: Not in version control	Assembly Variant: [No Variations]	Size: B
Drawn By: SHRIDHAR MORE	File: TID_Hardware_SchDoc	Contact: http://www.ti.com/support

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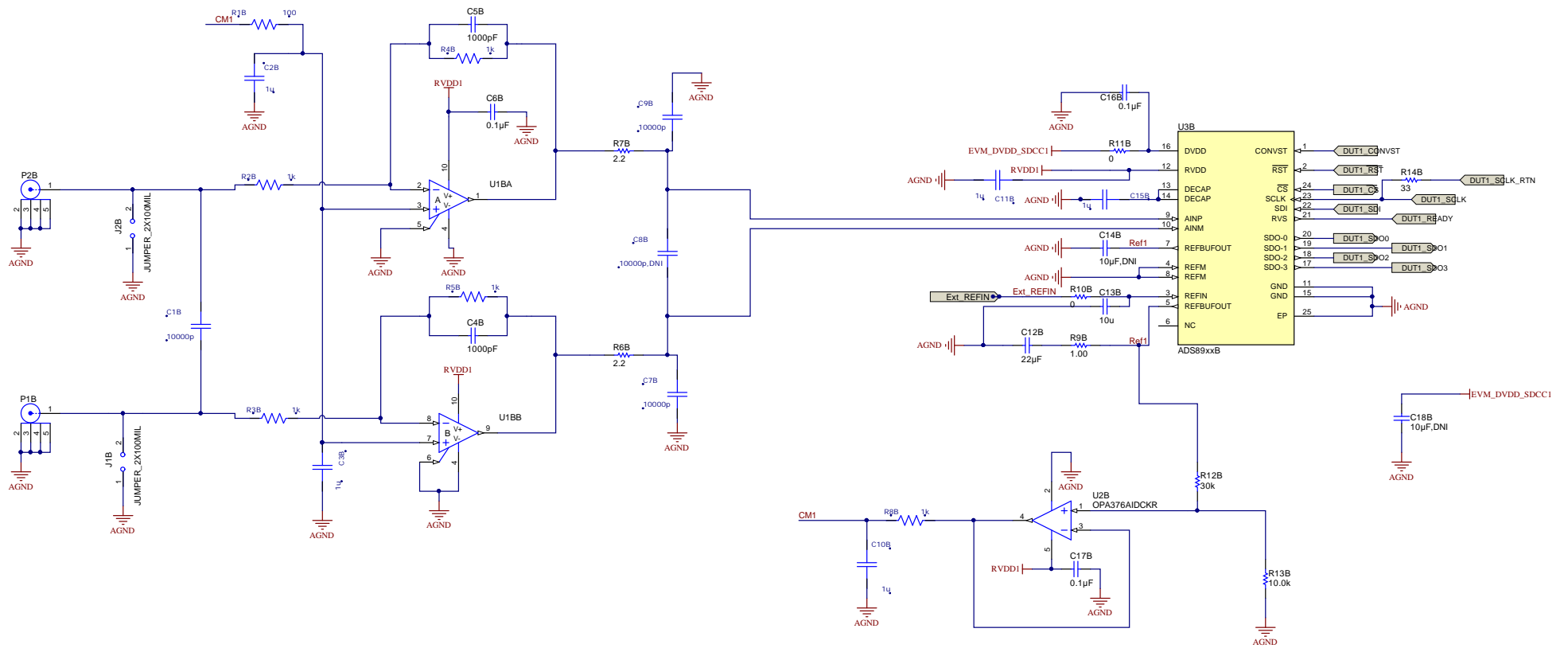


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TID #: TIPD211	Project File: TIPD211	
Number: TIPD211 Rev: E1	Sheet Title:	
Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 4 of 10
Drawn By:	File: DUT0_SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	

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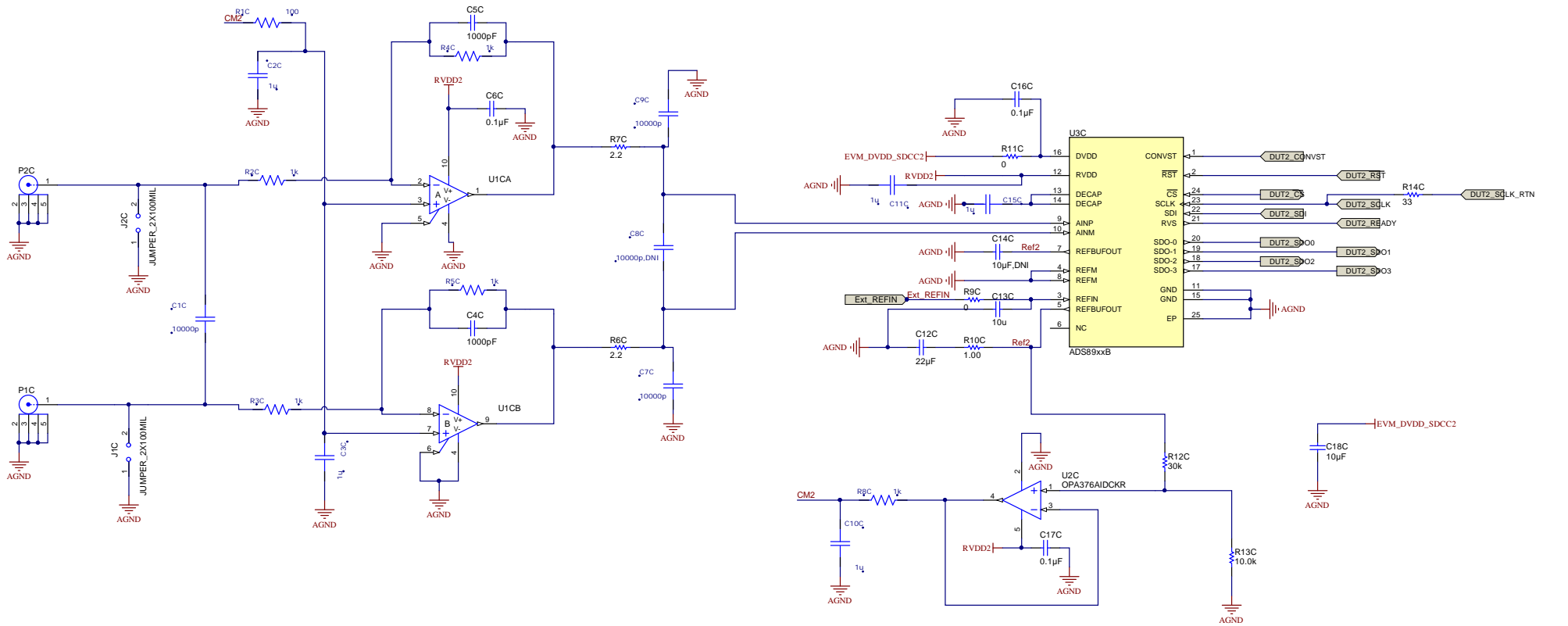


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TID #: TIPD211	Project Title: TIPD211	
Number: TIPD211 Rev: E1	Sheet Title:	
License: Rev. Not in version control	Assembly Variant: [No Variations]	Sheet: 5 of 10
Drawn By:	File: DUT1_SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	

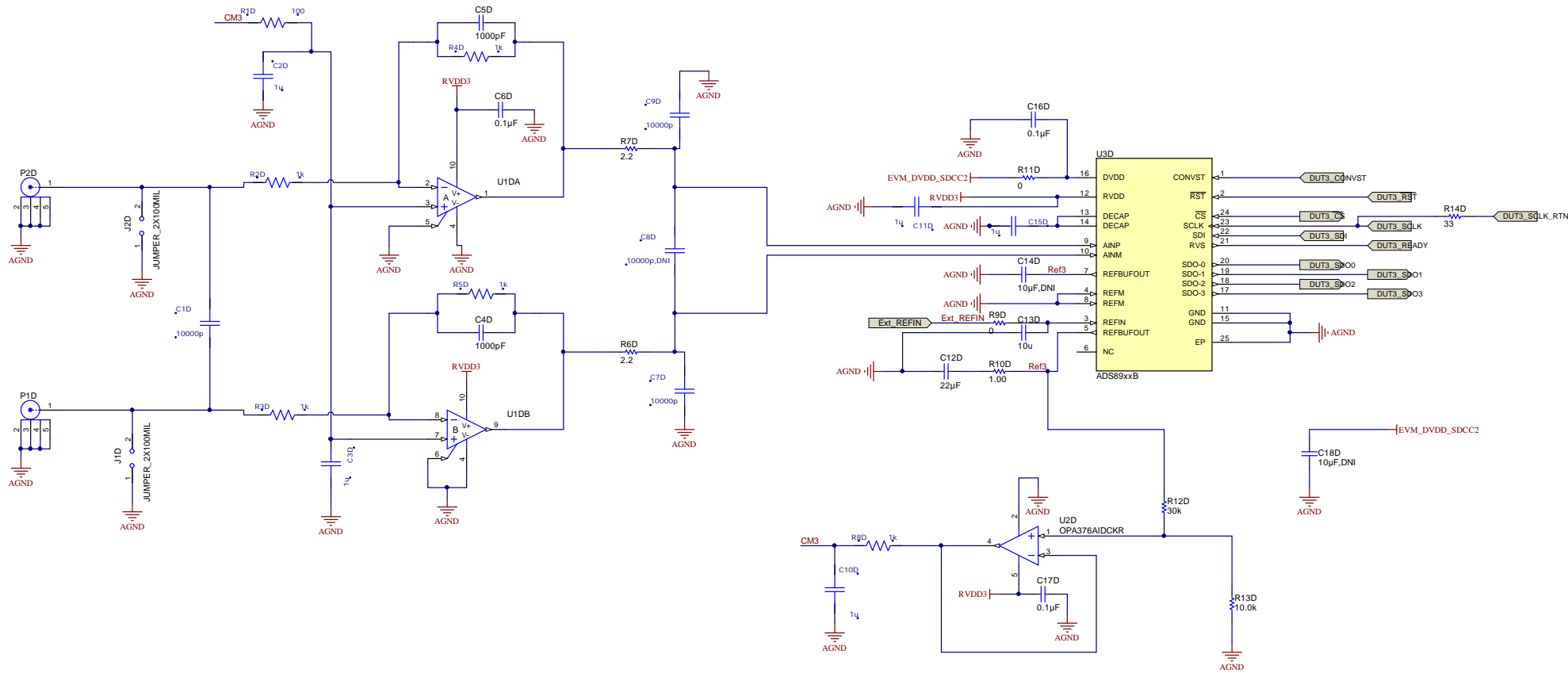
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TID #: TIPD211	Project Title: TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:
Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 6 of 10
Drawn By: SHRIDHAR MORE	File: DUT2_SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	

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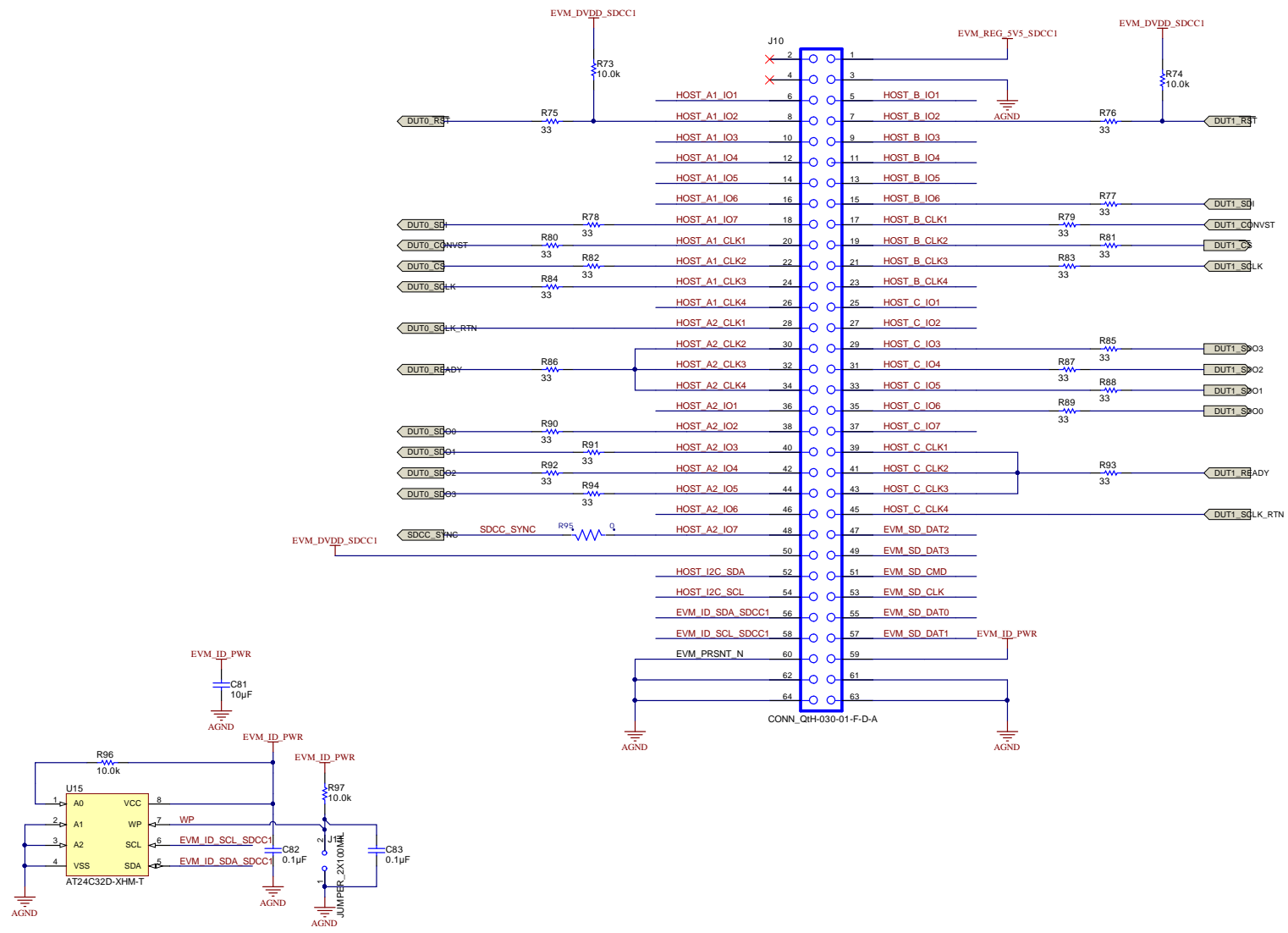


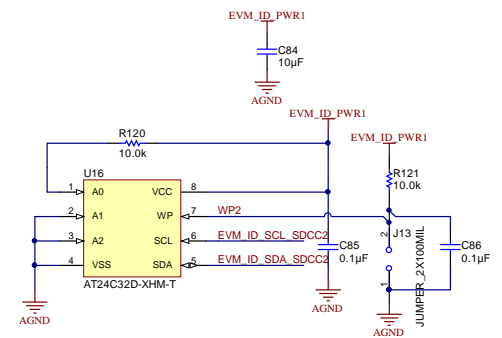
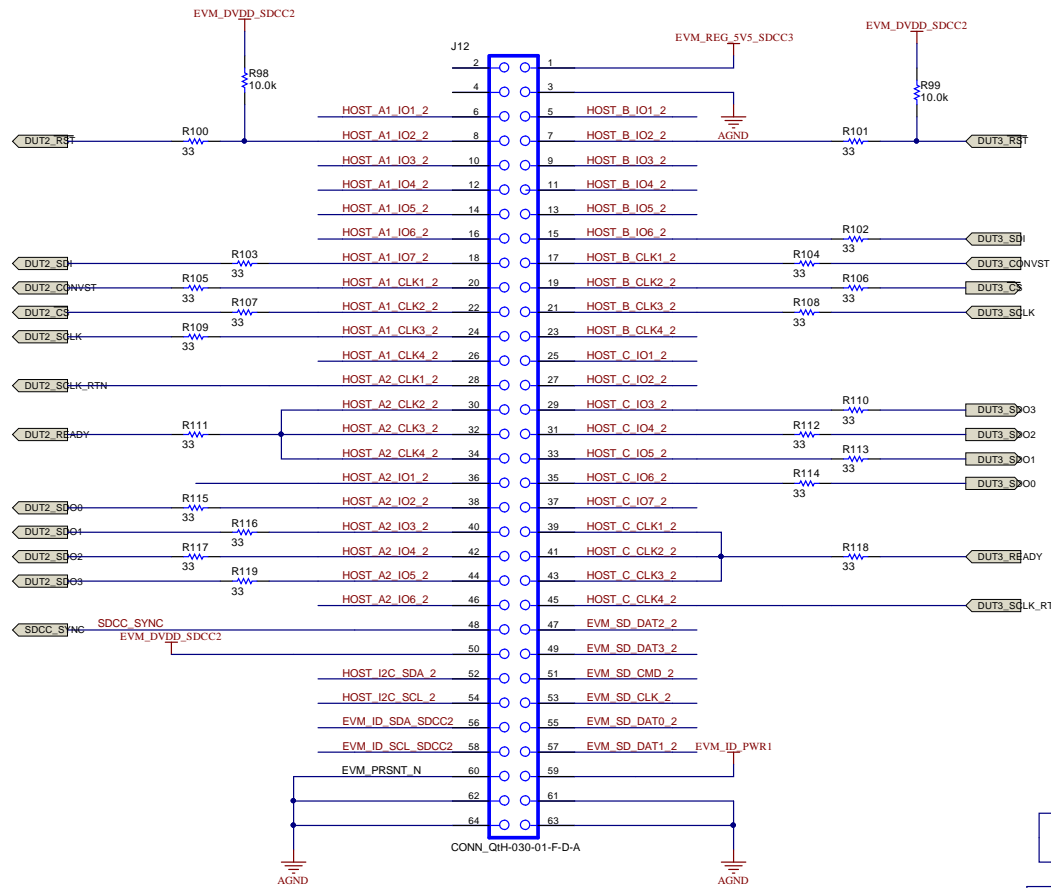


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Number: TIPD211	Rev: E1	Sheet Title:
Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 7 of 10
Drawn By:	File: DUT3_SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	



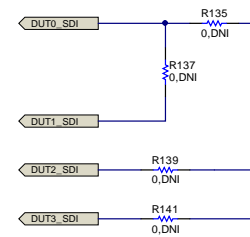
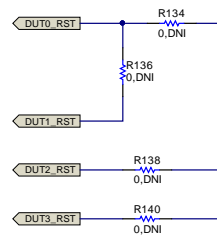
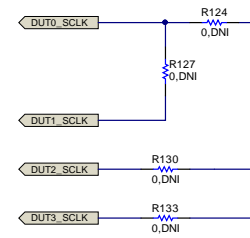
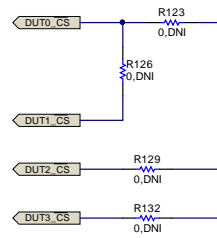
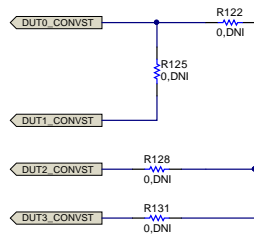





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TID #: TIPD211	Project Title: TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:
Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 9 of 10
Drawn By:	File: SDCC2 Connector.SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	

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Number: TIPD211	Rev: E1	Sheet Title:	
Rev: Not in version control	Assembly Variant: [No Variations]		
Drawn By: SHRIDHAR MORE	File: Simultaneous_Cap_SchDoc	Sheet: 10 of 10	
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	Size: B	

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